



## LGA7529 SOCKET AND HARDWARE

TE Connectivity's (TE) LGA7529 socket for next-generation server processors provides more connections between the motherboard and the processor. With 7529 pins, the socket delivers increased performance and data bandwidth to support top processor next-generation multi-core architectures and high-throughput workloads, enabling the latest server architectures for data centers and artificial intelligence (AI).

### APPLICATIONS

- Hyperscale / Datacenter
- Networking Equipment
- AI / Machine Learning
- Edge Computing
- HPC
- Cloud Service
- Servers
- Switches

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### FEATURES & BENEFITS

#### High Performance

- Great number of pin counts enhances connectivity between the CPU and other components
- Good scalability for next generation processors
- Better thermal management for high-performance operations

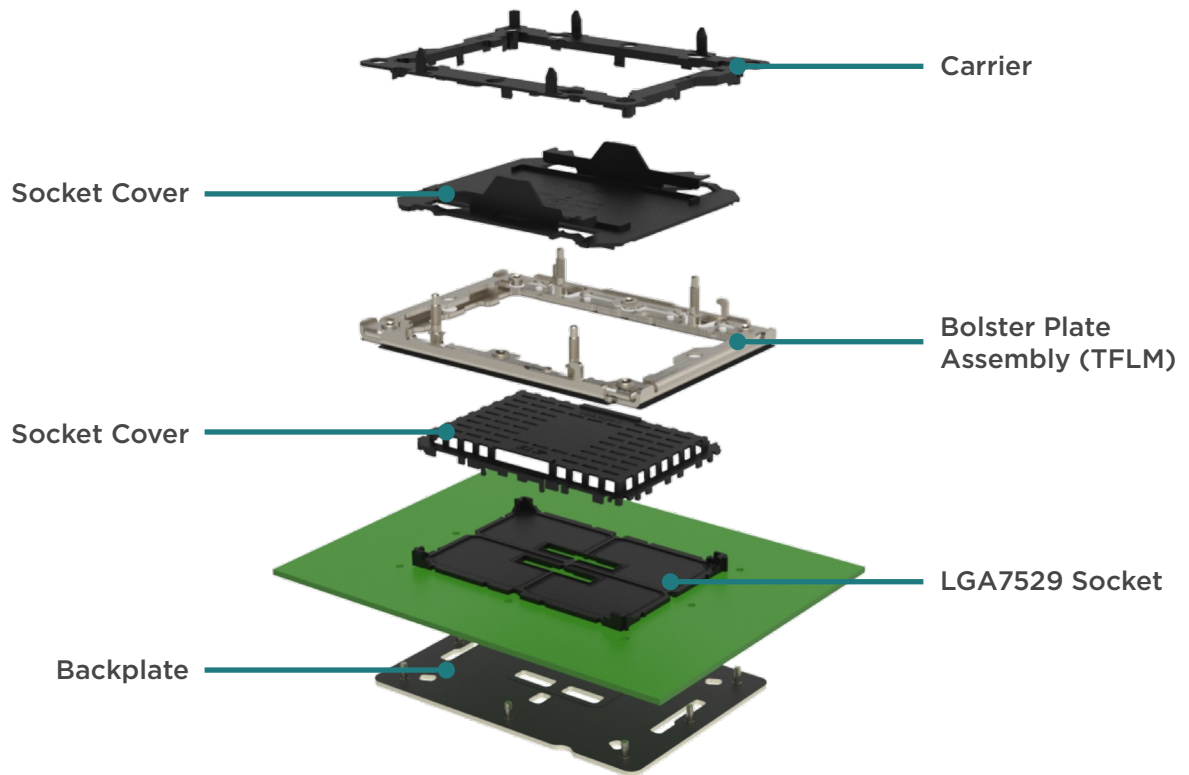
#### Next Generation Hardware

- Supports PCIe 5.0 technology – providing faster speeds and greater efficiency, ensuring compatibility with advanced GPUs, network cards, and storage devices
- Supports 12-channel DDR5 DRAM memory that allowing processors to connect with multiple memory channels for high bandwidth

#### Reliable and Easy Installation

- Qualified and tested durability, environmental resistance, shock and vibration
- Supports auto-assembly processes to facilitate ease of installation and limit possibility of rework
- Continuing cost optimization

## LGA7529 SOCKET AND HARDWARE



	Part Number	Part Description
LGA7529 Socket	<a href="#">2375157-1</a>	LGA7529 Socket, 30u" Gold Plating
LGA7529 Hardware	<a href="#">1-2376820-1</a>	LGA7529 Bolster Plate Without Dust Cover
	<a href="#">1-2376820-2</a>	LGA7529 Bolster Plate With Dust Cover
	<a href="#">2376821-1</a>	Back Plate (PCB: 2.36mm-2.74mm) (PCB: 0.093"-0.108")
	<a href="#">2376821-2</a>	Back plate (PCB: 2.77mm-3.15mm) (PCB: 0.109"-0.124")
	<a href="#">2376821-3</a>	Back plate (PCB: 3.175mm-3.556mm) (PCB: 0.125"-0.140")
	<a href="#">1-2376822-1</a>	LGA7529 Carrier BR1A
	<a href="#">2376823-1</a>	LGA7529 Carrier BR1B
	<a href="#">2376822-2</a>	LGA7529 Socket Cover

## FAQ

- **Q:** What is the Au plating thickness, 15u" or 30u"?"  
**A:** 30u"
- **Q:** Can we use another supplier's Hardware along with TE's LGA7529 Socket?  
**A:** We recommend use TE CPU Socket & Hardware with better service support
- **Q:** What's the CPU platform support?  
**A:** TE's LGA7529 Socket supports to the next-generation server processors: Birch Stream; CPU code name: Granite Rapids-AP/Sierra Forest-AP/Clearwater Forest-AP
- **Q:** What is dimension of LGA7529 Socket housing?  
**A:** 112.5mm x 75.5mm
- **Q:** Can TE's LGA7529 Socket support DDR & PCIe technologies?  
**A:** TE's LGA7529 Socket supports DDR5 & PCIe Gen5

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